



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
)  
Appl. No. : 10/823,970 ) Confirmation No. 5318  
Applicant : OGAWA, et al. )  
Filed : 13 April 2004 )  
Art Unit : 2818 )  
Examiner : Hoang, Quoc Dinh )  
Attorney : )  
Docket No. : AMD-AF01215 )  
)  
For: SEMICONDUCTOR DEVICE HAVING )  
A PAD METAL LAYER AND A LOWER METAL )  
LAYER THAT ARE ELECTRICALLY )  
COUPLED, WHEREAS APERTURES ARE )  
FORMED IN THE LOWER METAL LAYER )  
BELOW A CENTER AREA OF THE PAD )  
METAL LAYER )  
\_\_\_\_\_ )

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE RCE

Dear Sir:

In response to the Final Office Action dated December 23<sup>rd</sup>, 2005, and the notice of panel decision dated April 10, 2006, Applicants respectfully submit the following regarding the above captioned patent application. Amendments to the Claims begin on page 2 of this response. Remarks begin on page 5 of this response.

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Serial No.: 10/823,970  
Group Art Unit: 2818